

Title (en)

HEAT TREATMENT METHOD AND HEAT TREATMENT DEVICE

Title (de)

WÄRMEBEHANDLUNGSVERFAHREN UND WÄRMEBEHANDLUNGSVORRICHTUNG

Title (fr)

PROCÉDÉ DE TRAITEMENT THERMIQUE ET DISPOSITIF DE TRAITEMENT THERMIQUE

Publication

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Application

EP 17703347 A 20170125

Priority

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Abstract (en)

[origin: WO2017137259A1] The invention relates to a method and a device for the heat treatment of a steel component directed specifically at individual zones of the component. In one or more first regions of the steel component, a primarily austenitic microstructure can be set and then transformed into a predominantly martensitic microstructure by quenching, and in one or more second regions of the steel component a predominantly bainitic microstructure can be set, wherein the metal component is first heated up in a furnace to a temperature above the AC3 temperature, the steel component is subsequently transferred to a treatment station, allowing the component to cool down during the transfer, and in the treatment station the one or more second regions of the steel component are cooled down during a treatment time to a cooling stop temperature ≥ 2 .

IPC 8 full level

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